# HKROC: digitizer description and test results

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#### **Part I: Introduction**

### Part II: The HKROC ASIC

**Part III: Test results** 

- HK physics program
- General description of HKROC
- HKROC history
- Key characteristics
- General description
- Block scheme
- Operating principle
- Calibration
- Noise evaluation
- Cross-talk measurements
- Time measurements
- Charge measurements



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Part III: Test results	<ul><li>Calibration</li><li>Noise evaluation</li></ul>	See Rudolph's
	Cross-talk measurements	presentation
	<ul> <li>Time measurements</li> </ul>	I
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See Rudolph's presentation



## Part I: Introduction

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Solar neutrinos
MSW effect in the sun
NSI in the Sun

Supernova



Proton decay Ul AAU Próbe GUT

- Observe CP violation for leptons at 5σ
- Precise measurement of  $\delta_{CP}$  .
- High sensitivity to v mass ordering.







### Large physics program $\Rightarrow$ Strong requirements on electronics

#### **HK = challenging measurements:**

- complex topologies: e.g. multiring samples
- large energy range: from SN to HE physics
- Michel-electron tagging
- neutron tagging

#### **HK = challenging systematics:**

- PMT response.
- Water transparency
- Direct vs indirect light
- Huge scale

### Strong requirements on electronics:

- on charge measurements
- on timing measurements
- on hit rate and dead time



### Large physical program $\Rightarrow$ Strong requirements on electronics

Physics constraint	Impact on electronics requirement
Detect synchronous (beam) & asynchronous (atm., solar, p-decay, SN) events	Self triggering for each channel
Detect close SN (e.g. Beltegeuse) w/ no event loss	Channel dead time $< 1 \ \mu s$
Detection threshold as low as possible (negligible noise compared to PMT one)	Charge threshold <= 1/6 p.e.
Excellent detection & no charge ↔ E bias from low (solar, SN) to high energy physics	Charge linearity < 1 % from 0 to 2500 pC (0 to 1250 p.e. for HK)
Excellent charge $\leftrightarrow$ E resolution	Charge RMS <= 1%
Electronics < PMT time resolution (1.3 ns)	Electronics timing RMS < 0.3 ns at 1 p.e.
Low power consumption as under water	1 W/ channel

Microelectronics

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Microelectronics

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Self triggering for each channel

Channel dead time  $< 1 \, \mu s$ 

Charge threshold <= 1/6 p.e.

Charge linearity < 1 % from 0 to 2500 pC (0 to 1250 p.e. for HK)

Charge RMS <= 1%

Electronics timing RMS < 0.3 ns at 1 p.e.

1 W/ channel

# The challenge was taken up

# LLR, OMEGA and CEA present





# Advanced ASIC chip for PMT readout

#### **Part I: Introduction**

Hyper-Kamiokande Read Out Chip - ASIC designed read out of the PMT of the future Hyper-Kamiokande experiment.

The HKROC is a waveform digitizer: it reconstructs the full shape of the charge-signal waveform and provides extremely precise timing measurement.









#### **Part I: Introduction**

We found significant cross-talk! Well, let's do the new version and find students to test it



#### History

- Derived from the **CROC** chip originally designed for the CMS High Granularity Calor.
- The first HKP c version was designed in 2021
- Lab test, nave been conducted since January 2022

Intensive tests on new versions\*



- In December 2022 new version of mother board with BGA-packaged HKROC arrived (was designed to avoid closed cross-talk, see details later)
- In February 2023 new version of chip HKROC v1b arrived (was designed to avoid diffuse cross-talk)

The results of our tests in the last part will be based on v1b BGA-packaged version





Very precise timing characteristics Even exceed the requirements

1 W/ channel



## Part II: The HKROC ASIC

- General description
- Block scheme
- Operating principle

#### Part II: The HKROC ASIC



High gain channels Medium gain channels Low gain channels

> 1 HKROC II 36 channels II 12 PMTs





Each channel includes converters for the charge and the time measurements:

- 10-bit 40 MHz Analog-to-Digital Converter (ADC)
- 10-bit Time-to-Digital Converter (TDC) (designed at CEA IRFU)



All the relevant data (charge and time) are stored into local memories (depth 32) and then read out through four high speed differential links sending data at 1.28 Gb/s.

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### **Part I: Introduction**

#### **Operating principle**

Shapes the PA output signal to allow the charge measurement, to optimize the signal-to-noise ratio and use the full available dynamic range (1.2 V).

After preamplification signal follows two paths:

A slow path with shapers connected to the ADC for charge measurement

ADC

A fast path with a discriminator connected to the TDC for time measurement (dead time 30 ns)

SH



10

20

30

Time [ns]

40

50

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PA

trigger on the signal above a set

threshold.

60



## Part III: The results of the performed tests



Charge measurements

#### Part III: Test results

### Calibration

Step I: Stardartisation of DC level

**Goal**: the pedestal level should be uniform for all channel to have the same dynamic range.

#### For this purpose:

- ADC is measured is absence of injected charge to measure the pedestal.
- Using slow control parameters the pedestals are changed to be as uniform as possible



MEGA

#### Part III: Test results

### Calibration

#### Step II: Trigger threshold channel by channel

Goal: The level of triggering threshold for each should be a set at specific level (HK requirement – 1/6 p.e)



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## Calibration

#### Step II: Trigger threshold channel by channel

Firslty, we werform threshold scan channel by channel using a **global** slow control parameter



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# Microelectronics

## Calibration

#### Step II: Trigger threshold channel by channel

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### Calibration

#### Step II: Trigger threshold channel by channel

Firslty, we werform threshold scan channel by channel using a **global** slow control parameter



#### Part III: Test results



### Calibration

#### Step II: Trigger threshold channel by channel

#### The global level is set after the scan


Calibration



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## **Noise level evaluation**



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## **Cross-talk measurements**







#### Reminder



**Second** version of board (**board v2 BGA**) was designed mainly to reduce **close cross-talk** what was discovered for first version of board.

**Second** version of chip (**HKROC v1b**) was designed mainly to reduce **diffuse cross-talk** what was discovered for first version of chip.

#### Close cross-talk = cross-talk in neighboring channels of the injected channel Diffuse cross-talk = cross-talk all channels

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#### Diffuse cross-talk matrices – Board v2 (BGA)



Indeed, diffuse XT came from the chip

#### Part III: Test results



#### Diffuse cross-talk distribution (taking amplitudes of diff. XT from all channels)



# From chip v0 to v1b: Factor 3 of reduction of diffuse XT Diffuse cross-talk level: 0.12 p.e.

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#### **Close cross-talk matrices – chip v1b**



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Biweekly meeting-Apr 25<sup>th</sup>, 2023



#### Close cross-talk distribution (taking amplitudes of diff. XT from all channels)



Board v1 (Mezzanine)

Board v2 (BGA)

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Why close cross-talk was reduced?

The BGA-packaged HKROC has been designed so its input lines are alternated on two different layers separated by a ground layer.





#### **Conclusion of cross-talk measurements**

**Diffuse cross-talk:** From chip v0 to v1b: Factor 3 of reduction Diffuse cross-talk level: 0.12 p.e.

#### Close cross-talk:

Suppression of the close cross-talk : HG ch. → HG + LG ch. Survival 1-2 % close cross-talk: HG ch. → MG ch. Abnormal 5-6% close cross-talk HG ch. 15 → LG ch. 14.



#### **Time measurements**

Example for channel 21



#### **Part III: Test results**



#### **Time measurements**



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#### **Time measurements**





# Part III: The results of the performed tests

- Calibration
- Noise evaluation
- Time measurements
- Cross-talk measurements
- Charge measurements



# Part III: The results of the performed tests

# **Charge measurements**

Benjamin Quilon: "Be aware, it is the trickiest part of the analysis" Rudolph and Denis: "Thanks for motivation!"

We are close to the end...



# Algorithm for charge reconstruction

#### **Step 1: Building the reference waveform**

It can be waveform corresponding to 1 p.e., for instance





#### Algorithm for charge reconstruction

#### **Step 2: Digitisation of the waveforms for other charges**

For each waveform from 3 to 7 points can be digitised























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Example for channel 0





# Step 4: Charge inference from $\chi^2$

 $\chi^2(q)$ 





### Step 4: Charge inference from $\chi^2$





#### **Part III: Test results**

MEGA Microelectronics

#### Results

Example for channel 0



#### Part III: Test results

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# Plans

• Finish charge reconstruction for all channels

• Measure the effect of cross-talk on charge reconstruction

• Write a paper for last version of HKROC (summer 2023)



# The end to be continued...

"Completely no pressure but finish the tests by the end May"

Benjamin



#### **Time measurements**

Bump noise depends on relative phase between internal clock and input signal





#### **Time measurements**

Bump noise depends on relative phase between internal clock and input signal



#### **Part III: Test results**

#### **Time measurements**

Bump noise depends on relative phase between internal clock and input signal



BACKUP





#### **Time measurements**



#### **Part III: Test results**



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The HKROC ASIC is designed in TSMC 130 nm technology.

- 1. An analog front end part that allows the input signal amplification, the trigger detection and the signal shaping ;
- 2. A mixed part to provide the charge and time of arrival measurements
- 3. A digital part to manage all the system, the conversion and the read-out.

## Backup



Analog part

- 1. PA provides the first amplification of the PMT signal with the best noise performances. The preamplifier provides two outputs: an output connected to the TOA discriminator for the time of arrival measurements and a second output, through a buffer, connected to the shaper path to allow charge measurement.
- 2. The purpose of this slow path is to shape the PA output signal in order to allow the charge measurement, to optimize the signal-to-noise ratio and use the full available dynamic range (1 V).
- 3. The trigger path (green part in Fig. 2.1) is responsible for the trigger formation. The PA signal is sent to a low offset discriminator which allows to auto trigger on the signal above a set threshold. The threshold is set by a global 10b-DAC (tuneable by SC) and a local trimming 6b-DAC (tuneable by SC) to reduce the dispersion per channel. The trigger signal is sent to the TDC block for the measurement of the arrival time.



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**Biweekly meeting-**Apr 25<sup>th</sup>, 2023



Mixed part

The HKROC contains a 10b SAR ADC, designed by AGH in Krakow.

The timing channel that generates the precise ToA (time of arrival) of the particle consists of a discriminator followed by a TDC circuit. The Charge Sensitive Amplifier (CSA or pre-amplifier) output voltage is compared to a reference voltage whose value is adjustable by slow-control and corresponds to the trigger threshold.

This innovative multichannel TDC architecture is chosen for its conversion speed > 40 MHz and its intrinsic resolution of 25 ps. Its low power consumption is also a key point in the HyperKamiokande environment. Power consumption of less than 1W has been observed for 1 chip of 36 channels (12 PMT) including the interface cards (mezzanine, motherboard and KCU), so well inside the HyperKamioaknde specifications requiring <1 W per PMT channel.

BACKUP



## FIFO

The ASIC has 4 DATA FIFOs that are standard circular FIFOs. Each FIFO has a depth of 32 sampling points whereas each word contains 32 bits. If a physics event is digitized with 3 sampling points, a FIFO has a depth for 10 to 11 consecutive events. As a reminder, each sampling point consists of 10 words (normal-mode) or 4 words (supernova-mode).

## Normal mode

## Supernova-mode

Data Header	SN Dh	24b Timestamp				P	1	Data Header	SN Dh		24b Timestamp				1
Data Header	Chn #0	Dh	Η	10b TOA	10b ADC	Р	1	Data Header	Chn #0	Dh	Η	10b TOA	10b ADC	P	1
Data Header	Chn #1	Dh	Η	10b TOA	10b ADC	P	1	Data Header	Chn #3	Dh	Η	10b TOA	10b ADC	P	1
Data Header	Chn #2	Dh	Η	10b TOA	10b ADC	P	1	Data Header	Chn #6	Dh	Η	10b TOA	10b ADC	P	1
Data Header	Chn #3	Dh	Η	10b TOA	10b ADC	P	1								
Data Header	Chn #4	Dh	Η	10b TOA	10b ADC	P	1								
Data Header	Chn #5	Dh	Η	10b TOA	10b ADC	P	1								
Data Header	Chn #6	Dh	Η	10b TOA	10b ADC	P	1								
Data Header	Chn #7	Dh	Η	10b TOA	10b ADC	P	1								
Data Header	Chn #8	Dh	Η	10b TOA	10b ADC	P	1								

BACKUP

Noise->Bump in resolution A plot

Previous results

New results